The following specifications apply to all RF Micro Devices products.

Solderable Surface Finish

The following solderable surface finishes are used:

Package Style	Plating Material	Thickness
SOP-8-C	Au on Ni	Au max 1µm Ni 2-6µm
All plastic packages	SnPb (60/40) on Ni	SnPb min 6µm typ 12µm

Minimum Requirements for Shipping and Storing in Order to Preserve Reliability and Solderability

Minimum protection required: Cardboard box
Maximum shelf life with specified protection: 1 year

Expected Shipping and Storing Conditions:

Relative humidity 15% to 70%
Temperature -5°C to 40°C
Sulphur dioxide average 0.3mg/m^3
Sulphuretted hydrogen average 0.1mg/m^3

Component Coplanarity

Determination of coplanarity: solderable lead deviation from the reference plane formed by three lowest contact points when component lies on flat surface by its own weight.

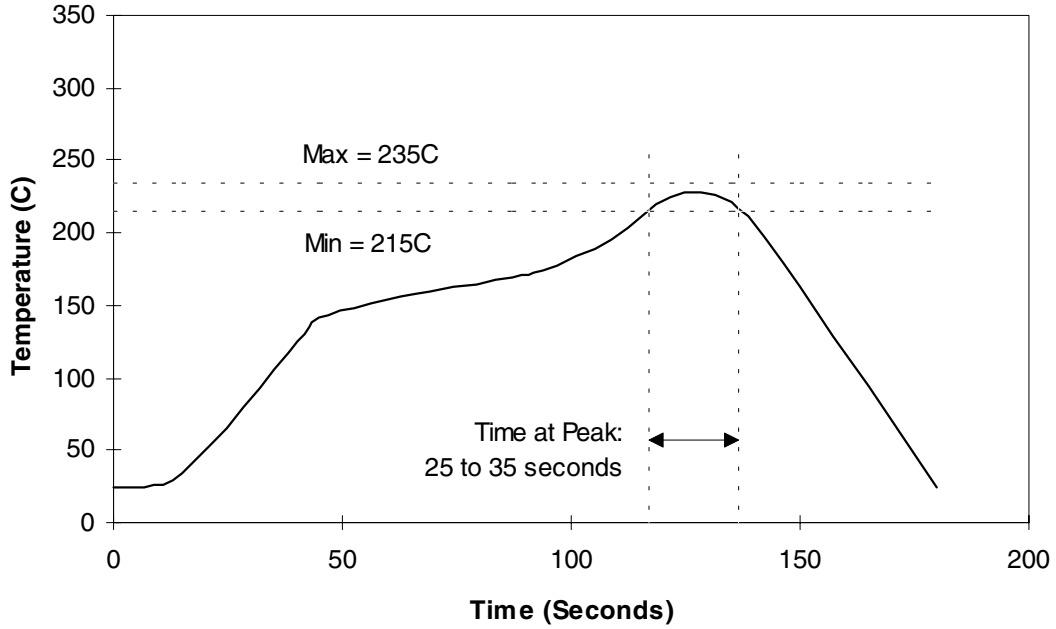
Coplanarity specification: max 0.004 inches

Solderability

Test equipment: wetting balance analyzer Multicore MUST System II

Specification: wetting speed 1.0 s to 2/3 F_{max}

Recommended Reflow Soldering Profile



Maximum temperature slope: 5°C/second
Product can withstand this profile two times.

Manual Hot Gas Soldering
Maximum air temperature: 300°C
Maximum air velocity: 10m/s
Maximum exposure time: 30s

Manual Soldering Using Soldering Iron
Tip Diameter: Selected to fit application
Maximum tip temperature: 370°C
Antistatic protection: Required
Maximum exposure time: 3s